Packaging & Delivery
Packaging Details
Retail package: bottle
Delivery Time
3~5 days, exact time depends on quantity
BEST-705 Lead-free brand silver tin lead solder paste

product description BEST-solder (Tin) paste is the best choice of reballing IC . original BEST brand , Quality Verified $\begin{array}{c} \\ \\ \end{array}$

Application: can be used for laptop /computer/mobile phone/home Appliances SMD IC and BGA IC repairing ,tools for chip-levelrepairing and Electronics Manufacture line.

Technology Parameter

Model

BEST-705

Alloy composition:

Tin:99% / silver: 0.3% / copper:0.7%

Melting point : 226-229 °C

Tin powder particle size:

 $25-45/\mu m$

Tin powder shapes:

spherical

Metal content:

 $89.5 \pm 1\%$

Refrigeration temperature:

 $5 \sim 10$ °C

N.W.:

50g/pc

What we can provide you with?

This product is produced for mobile phone repairing including 9 different types.

You can buy them separate, or can buy them 5pcs per set. You can make any combination of these 9 types for one set for your order.

Why choose us?

- 1. With 16 years experience in this field, we have the ability to provide good service and products in low cost
- 2. Adequate inventory assures enough products supplyment to our clients in a short period.

Product show





Name: Solder paste Model: BST-705

Size: \$\phi 35*20mm Weight: 40g

Composition: SN99/AG0.3/CUO.7 Melting point: 226℃~229℃





Storage:Chilled in refrigerator, the best refrigeration temperature is 5°C~10°C.

Features: 1. When continuous printing, its viscosity changes less, which can obtain very stable printing.

- 2. The circuit with the spacing of 0.4-0.6mm and above can complete fine printing.
- 3. With excellent weld ability, it can show proper viscosity in different parts.
- 4. It is suitable for the return welding furnace of general atmosphere and nitrogen.
- 5. Good weldability can be obtained at extremely high peak temperature.

PRODUCT PHOTOGRAPH







